



Message from the Editor

Here, we offer the sixth volume of Transactions of The Japan Institute of Electronics Packaging (Trans. JIEP). I believe that there is no doubt Trans. JIEP will yield valuable information to researchers and engineers in the field of microelectronics packaging technologies. Again this year, I will make a most cordial acknowledgment to all the people involved in publishing Trans. JIEP, including the authors, the reviewers/referees, the editorial committee members, society members, and the secretariat. This year's volume contains excellent and attractive papers in the field of 3-D packaging, Si-TSV, thermal management (cooling and heat dissipation), optical interconnection, nano/micro-bonding, new materials/material engineering, power electronics, biomimetics, and so on.

The distinguishing feature of this year's volume is that there are some papers focused on emerging technological fields such as nano-bonding, power electronics, and biomimetics. These new technologies are expected to play an important role in reviving the Japanese electronics industry by combining with a new market. I believe that the Japanese has an ability to continue to develop new technologies and markets. Meanwhile, to achieve this, I think that it is important to pursue quality and to learn natural providence with a broad vision. I look forward to you submitting such kinds of original papers to Trans. JIEP.

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